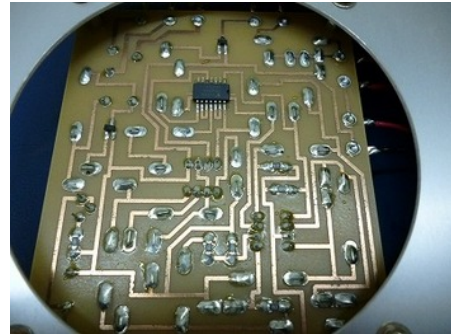
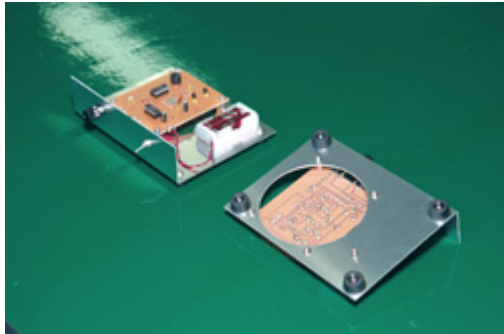


Soldering and Assembling Course

ISEE Engineering Division

1. Course outline

Soldering is indispensable for manufacturing an electronics device. Many students learn soldering by watching others and the reliability of their skill seems to be questionable in many cases. The National Trade Skill Test (<http://www.javada.or.jp/english/index.html>) for “Electronic Equipment Assembling (EEA), Grade 3” is known to be a good measure for having reliable soldering skill. This course will instruct you the knowledge and technical skill required for Grade 3 of the EEA. An electronic device for photon detection will be used for the training material.



Training material

2. Date, place and remarks

Date: May 23rd and 24th

*) The arrangement of the second day can be negotiable upon your request.

**) Taking a written exam is required to earn the LGS credit after participating the course.

Place: Institute for Space-Earth Environmental Research (ISEE), Research Institute Bldg. I,
Room 209 and workshop.

Quota: 6 persons

Just bring your writing instruments. Teaching/training material and tools will be prepared for you. English support is available in best-effort basis, but the capability of Japanese conversation is required at some level. Please consult with the contact person for details.

3. Schedule

	9:00 - 12:00 am	1:20 – 5:00 pm
May 23 (Wed)	- Lecture on the soldering theory - Work instruction	- Basic exercise for soldering (including surface mounting)
May 24 (Thu)	- Soldering on a printed wiring board (including surface mounting)	- Soldering for wiring and connectors - Assembling, operation check, etc.

4. Registration

Send an e-mail to the contact address shown below with the following information.

– Subject: “Registration for soldering and assembly”

– Description: name, department, research group, grade and e-mail address

The application deadline is 15:00, May 21st.

Contact address:

Yasusuke Kojima (ISEE Engineering Division)

Tel: 052-789-4321 (ext. 4321)

E-mail: yasusuke@isee.nagoya-u.ac.jp